

Abstract of the Disclosure:

According to the invention, one or more external test connection contact points (pads; pins; balls), are provided in an integrated circuit component (chip) (1), through which signals (4, 5, 6) that are to be measured or analyzed are selectively fed, e.g. by means of a multiplex circuit (7,8), and wherein the signals may be connected by means of routes located internally in the component from switch points that are not directly accessible, e.g. points inside the chip (15 to 20) or covered contact points. The device according to the invention is particularly useful for highly integrated semiconductor chips.

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